

2200537

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DIN rail housing, Lower housing part with metal foot catch, with 3 FE contacts, tall design, with vents, width: 67.8 mm, height: 99 mm, depth: 107.3 mm, color: light gray (similar RAL 7035), cross connection: integrated bus connector, number of positions cross connector: 5+2, Bus connector: 5 parallel contacts, 2 serial contacts

Your advantages

- · Tool-free mounting
- Available in overall widths from 12.5 mm ... 90 mm, modular extension is possible
- · Flammability rating V0 in accordance with UL 94
- · Variety of connection technology
- Can be mounted on the DIN rail
- With integrated or DIN-rail-mountable bus connector as an option

Commercial data

Item number	2200537
Packing unit	10 pc
Minimum order quantity	10 pc
Sales key	ACHAAB
Product key	ACHAAB
Catalog page	Page 665 (C-1-2013)
GTIN	4046356608039
Weight per piece (including packing)	105.6 g
Weight per piece (excluding packing)	105.6 g
Customs tariff number	85369010
Country of origin	DE



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Technical data

Notes

Assembly note	Please observe the application note in the download area.
Recommendation	Material of contact pads for bus connector, galvanic gold (hard gold)

Product properties

Product type	Enclosure bottom part
Housing type	DIN rail housing
Housing series	ME
Product family	ME 67,5
Max. number of positions	0)
Туре	Lower housing part with metal foot catch, with 3 FE contacts, tall design
Ventilation openings present	yes

Dimensions

Dimensional drawing	d
Width	67.8 mm
Height	99 mm
Depth	107.3 mm
Depth from top edge of DIN rail	100.7 mm
Depth from top edge of DIN rail to support point on upper part	68.5 mm
PCB design	
PCB thickness	1.4 mm 1.8 mm

Material specifications

Color (Housing)	light gray (RAL 7035)
Flammability rating according to UL 94	V0
CTI according to IEC 60112	600
Housing material	PA
Surface characteristics	untreated

Environmental and real-life conditions

Power dissipation single housing for 20 °C



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Ambient temperature	20 °C
Reduction factor	1
Mounting position	vertical
Power dissipation	9.1 W
De continuitation distribution distribution (c. 00 °C)	
Power dissipation single housing for 30 °C	20.00
Ambient temperature	30 °C
Reduction factor	0.91
Mounting position	vertical
Power dissipation	8.3 W
Power dissipation single housing for 40 °C	
Ambient temperature	40 °C
Reduction factor	0.81
Mounting position	vertical
Power dissipation	7.4 W
Power dissipation single housing for 50 °C	
Ambient temperature	50 °C
Reduction factor	0.7
Mounting position	vertical
Power dissipation	6.4 W
i ower dissipation	0. 4 vv
Power dissipation single housing for 60 °C	
Ambient temperature	60 °C
Reduction factor	0.57
Mounting position	vertical
Power dissipation	5.2 W
Power dissipation single housing for 70 °C	
Ambient temperature	70 °C
Reduction factor	0.49
Mounting position	vertical
Power dissipation	4.6 W
Vibration test	V=0 00000 0 0 000= V0
Specification	IEC 60068-2-6:2007-12
Frequency	10 - 150 - 10 Hz
Sweep speed	1 octave/min
Amplitude	0.15 mm (10 Hz 58.1 Hz)
Acceleration	2g (58.1 Hz 150 Hz)
Test duration per axis	2.5 h
Test directions	X-, Y- and Z-axis
Glow-wire test	
Specification	IEC 60695-2-11:2014-02
Temperature	



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Specification IEC 60695-10-2:2014-02 Temperature 125 °C Test duration 1 h Force 20 N Mechanical strength / tumbling barrel Specification IEC 60998-1:2002-12 Height of fall 50 cm Frequency 10 Shocks Specification IEC 60068-2-27:2008-02 Pulse shape Half-sine Acceleration 15 g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Variety Variety Variety Ambient temperature (storage/transport) 40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) 40 °C 100 °C Ambient temperature (assembly) 5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders 3 Type of PCB mount Insertion (optional latching by PCB stop) Thickness of the PCB 1.4 mm 1.8 mm Mounting type DIN rail mounting		
Specification IEC 60695-10-2:2014-02 Temperature 125 °C Test duration 1 h Force 20 N Aechanical strength / tumbling barrel Specification IEC 60998-1:2002-12 Height of fall 50 cm Frequency 10 Specification IEC 60068-2-27:2008-02 Pulse shape Half-sine Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Specification IEC 600529:1989-11 + AMD 1:1999-11 + AMD 2:2013-00 Ambient temperature (poration) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -40 °C 100 °C Relative humidity (storage/transport) -8 °C 100 °C Relative humidity (storage/transport) -10 °C Relative humidity (storage/transport)	Time of exposure	30 s
Temperature	Thermal stability / ball thrust test	
Test duration	Specification	IEC 60695-10-2:2014-02
Proce 20 N	Temperature	125 °C
Alechanical strength / tumbling barrel Specification Height of fall Frequency 10 Shocks Specification IEC 60988-1:2002-12 10 Shocks Specification IEC 60068-2-27:2008-02 Pulse shape Half-sine Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Subject of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Subject conditions Max. IP code to attain IP20 Ambient temperature (poration) Ambient temperature (storage/transport) Ambient temperature (storage/transport) Ambient temperature (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB In rail mounting Mounting type DIN rail mounting Ckaging specifications Type of packaging Packed in cardboard	Test duration	1 h
Specification IEC 60998-1:2002-12 Height of fall 50 cm	Force	20 N
Height of fall 50 cm	Mechanical strength / tumbling barrel	
Frequency 10 Shocks Specification IEC 60068-2-27:2008-02 Pulse shape Half-sine Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Pegree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -40 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders 3 Type of PCB mount Insertion (optional latching by PCB stop) Thickness of the PCB 1.4 mm 1.8 mm untting Mounting type DIN rall mounting ckaging specifications Type of packaging packed in cardboard	Specification	IEC 60998-1:2002-12
Shocks Specification IEC 60068-2-27:2008-02 Pulse shape Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions Xx, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders Type of PCB mount Thickness of the PCB 1.4 mm 1.8 mm Mounting type DIN rail mounting Mounting type DIN rail mounting Ckagging specifications Type of packaging packed in cardboard	Height of fall	50 cm
Specification IEC 60068-2-27:2008-02 Pulse shape Half-sine Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders 3 Type of PCB mount Insertion (optional latching by PCB stop) Thickness of the PCB 1.4 mm 1.8 mm untting Mounting type DIN rail mounting Type of packaging packed in cardboard	Frequency	10
Pulse shape Acceleration 15g Shock duration 111 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Selative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB I.4 mm 1.8 mm Nunting Mounting type DIN rail mounting Ckaging specifications Type of packaging Packed in cardboard	Shocks	
Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -5 °C 100 °C Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders 3 Type of PCB mount Insertion (optional latching by PCB stop) Thickness of the PCB 1.4 mm 1.8 mm untting Mounting type DIN rail mounting Ckaging specifications Type of packaging packed in cardboard	Specification	IEC 60068-2-27:2008-02
Shock duration Number of shocks per direction Test directions X-, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) 80 % B data Number of PCB holders Type of PCB mount Thickness of the PCB 1.4 mm 1.8 mm untting Mounting type DIN rail mounting Ckaging specifications Type of packaging packed in cardboard	Pulse shape	Half-sine
Number of shocks per direction Test directions X-, Y- and Z-axis (pos. and neg.) X-, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) -5 °C 105 °C Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Insertion (optional latching by PCB stop) Thickness of the PCB 1.4 mm 1.8 mm Punting Mounting type DIN rail mounting Ckaging specifications Type of packaging packed in cardboard	Acceleration	15g
Test directions X-, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders 3 Type of PCB mount Insertion (optional latching by PCB stop) Thickness of the PCB 1.4 mm 1.8 mm Functing Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Shock duration	11 ms
Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders Type of PCB mount Insertion (optional latching by PCB stop) 1.4 mm 1.8 mm Untting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Number of shocks per direction	3
Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders Type of PCB mount Insertion (optional latching by PCB stop) 1.4 mm 1.8 mm Untting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Test directions	X-, Y- and Z-axis (pos. and neg.)
Ambient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (storage/transport) Ambient temperature (assembly) -40 °C 55 °C Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders Type of PCB mount Insertion (optional latching by PCB stop) Thickness of the PCB 1.4 mm 1.8 mm unting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Degree of protection (IP code)	IFO 00500 4000 44 + AMD 4 4000 44 + AMD 0 0040 00
Max. IP code to attain IP20 Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders 3 Type of PCB mount Insertion (optional latching by PCB stop) Thickness of the PCB 1.4 mm 1.8 mm aunting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Specification	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-08
Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) -40 °C 55 °C Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders Type of PCB mount Insertion (optional latching by PCB stop) Thickness of the PCB 1.4 mm 1.8 mm aunting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Ambient conditions	
Ambient temperature (storage/transport) Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 80 % B data Number of PCB holders Type of PCB mount Insertion (optional latching by PCB stop) Thickness of the PCB 1.4 mm 1.8 mm nunting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Max. IP code to attain	IP20
Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB Mounting Mounting type DIN rail mounting Ckaging specifications Type of packaging packed in cardboard	Ambient temperature (operation)	-40 °C 105 °C (depending on power dissipation)
Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Insertion (optional latching by PCB stop) Thickness of the PCB 1.4 mm 1.8 mm nunting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Ambient temperature (storage/transport)	-40 °C 55 °C
Number of PCB holders Type of PCB mount Insertion (optional latching by PCB stop) Thickness of the PCB 1.4 mm 1.8 mm nunting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Ambient temperature (assembly)	-5 °C 100 °C
Number of PCB holders Type of PCB mount Insertion (optional latching by PCB stop) 1.4 mm 1.8 mm nunting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Relative humidity (storage/transport)	80 %
Type of PCB mount Insertion (optional latching by PCB stop) 1.4 mm 1.8 mm Funting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	CB data	
Thickness of the PCB 1.4 mm 1.8 mm Funting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Number of PCB holders	3
Thickness of the PCB 1.4 mm 1.8 mm Funting Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Type of PCB mount	Insertion (optional latching by PCB stop)
Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	Thickness of the PCB	1.4 mm 1.8 mm
Mounting type DIN rail mounting ckaging specifications Type of packaging packed in cardboard	ounting	
ckaging specifications Type of packaging packed in cardboard	-	DIN roll requesting
Type of packaging packed in cardboard	wounting type	raii mounting
	ckaging specifications	
Outer packaging type Carton	Type of packaging	packed in cardboard
	Outer packaging type	Carton

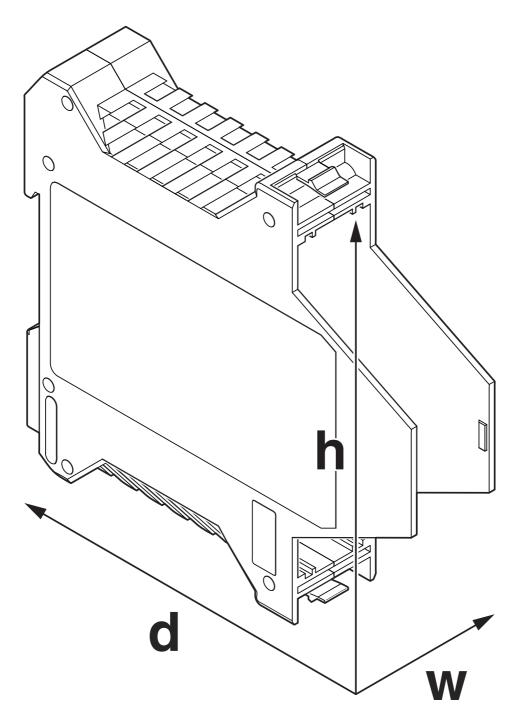


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Drawings

Dimensional drawing



Schematic figure for illustrating the item dimensions. The figure is not of the desired product. For further details, refer to the product drawings in the "Downloads" tab.



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Classifications

E	CLASS

	ECLASS-13.0	27190601	
Εī	ETIM		
	ETIM 9.0	EC002779	
1U	UNSPSC		
	UNSPSC 21.0	31261500	



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Environmental product compliance

EU RoHS

Fulfills EU RoHS substance requirements	Yes, No exemptions
China RoHS	
Environment friendly use period (EFUP)	EFUP-E
	No hazardous substances above the limits
EU REACH SVHC	
REACH candidate substance (CAS No.)	No substance above 0.1 wt%

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